

## 20V P-Channel Enhancement Mode MOSFET

### Description

The NP60P02D6 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ . This device is suitable for use as a load switch or in PWM applications.

### General Features

- ◆  $V_{DS} = -20V$   $I_D = -60A$   
 $R_{DS(ON)}(Typ.) = 3.8m\Omega$  @  $V_{GS} = -4.5V$   
 $R_{DS(ON)}(Typ.) = 4.4m\Omega$  @  $V_{GS} = -2.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ 150 °C operating temperature
- ◆ 100% UIS tested

### Application

- ◆ PWM applications
- ◆ Load switch
- ◆ Uninterruptible power supply

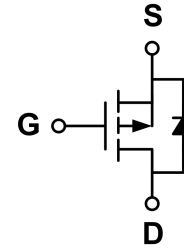
### Package

- ◆ PDFN5\*6-8L-A

*100% UIS TESTED!*

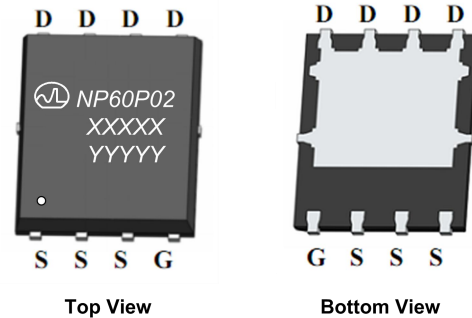
*100%  $\Delta V_{ds}$  TESTED!*

### Schematic diagram



### Marking and pin assignment

PDFN5×6-8L



XXXX—Wafer Information

YYYY—Quality Code

### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP60P02D6-G	-55°C to +150°C	PDFN5*6-8L-A	5000

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit	
Drain-source voltage	$V_{DS}$	-20	V	
Gate-source voltage	$V_{GS}$	±12	V	
Continuous Drain Current	$I_D$	TC=25°C	-60	A
		TC=70°C	-56	
Pulsed Drain Current	$I_{DP}$	-100	A	
Avalanche energy ( $T_j=25^\circ C$ , $V_{DD}=20V$ , $V_G=10V$ , $L=0.5mH$ , $R_g=25\Omega$ )	$E_{AS}$	69.8	mJ	
Power Dissipation	$P_D$	TC=25°C	104	W
		TC=70°C	100	
Operating junction Temperature range	$T_j$	-55—150	°C	

**Electrical Characteristics** (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V	-	-	1	μA
		T <sub>J</sub> =85°C	-	-	30	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.5	-0.6	-1.5	V
Drain-source on-state resistance <sup>1</sup>	R <sub>D(S)ON</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-30A	-	3.8	5	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-30A	-	4.4	6	
On Status Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-2.5V	66	-	-	A
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>SD</sub> =-30A, V <sub>GS</sub> =0V	-	-0.8	-1.3	V
Diode Continuous Forward Current	I <sub>S</sub>		-	-60	-	A
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =-30A, dI/dt=-100A/us	-	24	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	16	-	nC
<b>Dynamic Characteristics<sup>2</sup></b>						
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	-	4.2	-	Ω
Input capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-10V f=1.0MHz	-	8037	-	pF
Output capacitance	C <sub>OSS</sub>		-	753	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	665	-	
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>GS</sub> =-10V, V <sub>DD</sub> =-20V, R <sub>L</sub> =3Ω, I <sub>D</sub> =30A, R <sub>G</sub> =2.5Ω	-	14.2	-	ns
Turn-on Rise time	t <sub>r</sub>		-	35.4	-	
Turn-off delay time	t <sub>D(OFF)</sub>		-	361	-	
Turn-off Fall time	t <sub>f</sub>		-	224	-	
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-30A V <sub>DS</sub> =-10V	-	39.3	-	nC
Gate-source charge	Q <sub>gs</sub>		-	9.93	-	
Gate-drain charge	Q <sub>gd</sub>		-	17.9	-	

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	R <sub>θJA</sub>	20	34	°C/W
Maximum Junction-to-Ambient <sup>A</sup>		Steady-State	55	
Maximum Junction-to-Lead <sup>B</sup>	R <sub>θJC</sub>	1.2	2.5	

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

## Typical Performance Characteristics

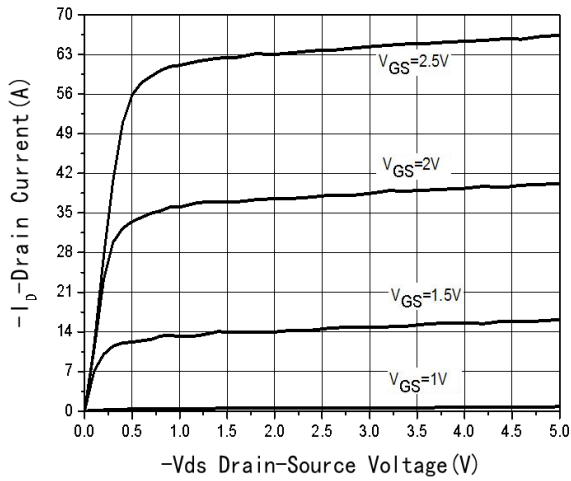


Fig1 Output Characteristics

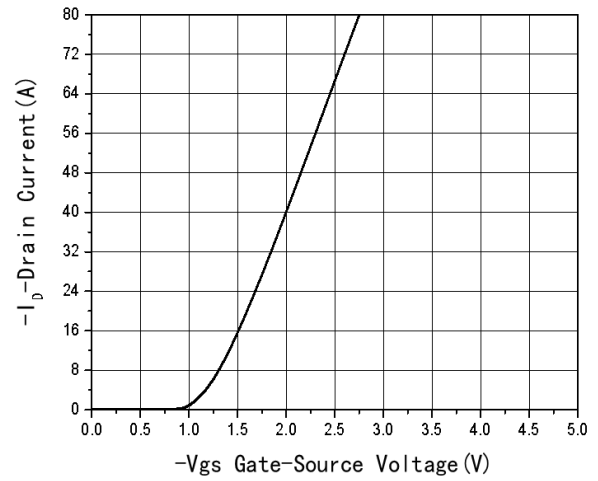


Fig2 Transfer Characteristics

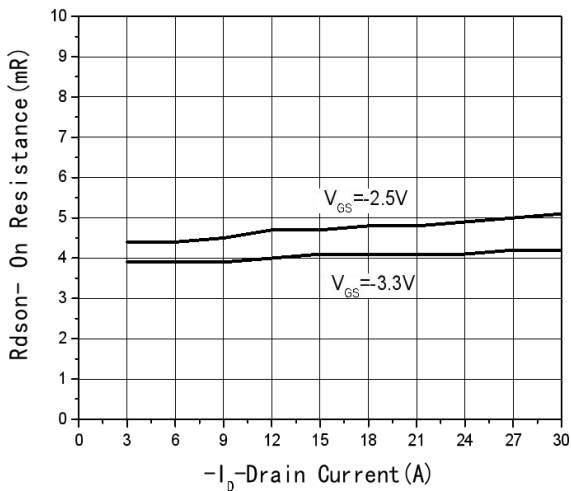


Fig3  $R_{dson}$ -Drain current

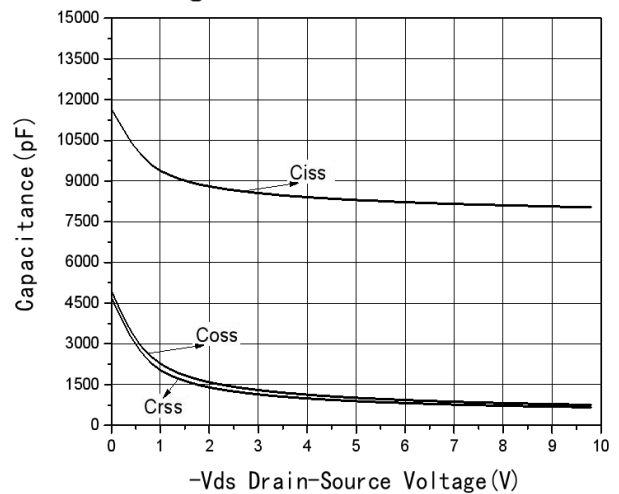


Fig4 Capacitance vs  $V_{DS}$

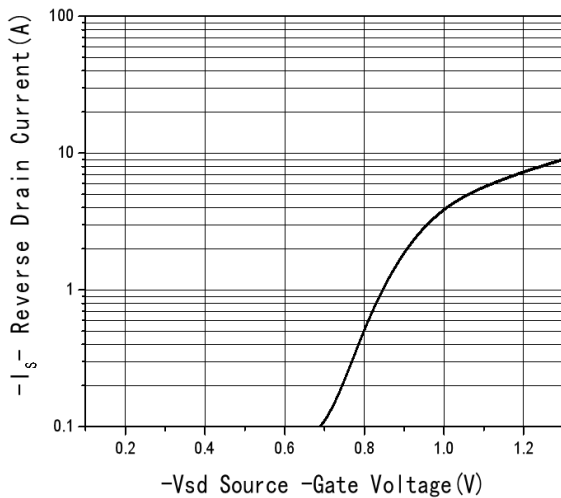


Fig5 Source-Drain Diode Forward

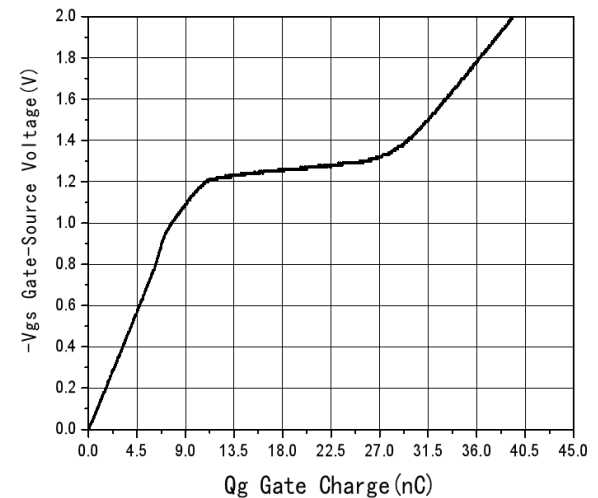
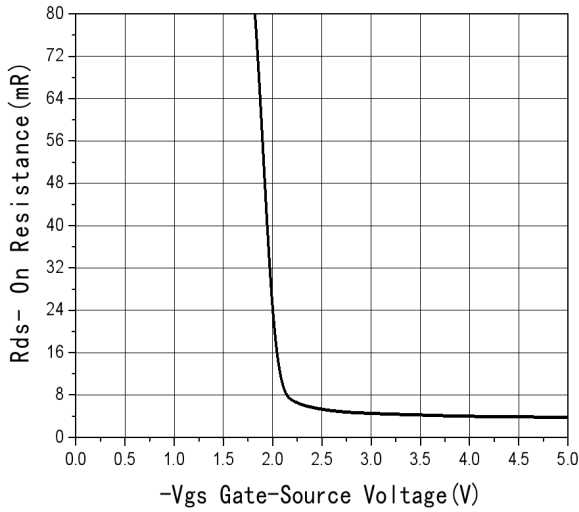
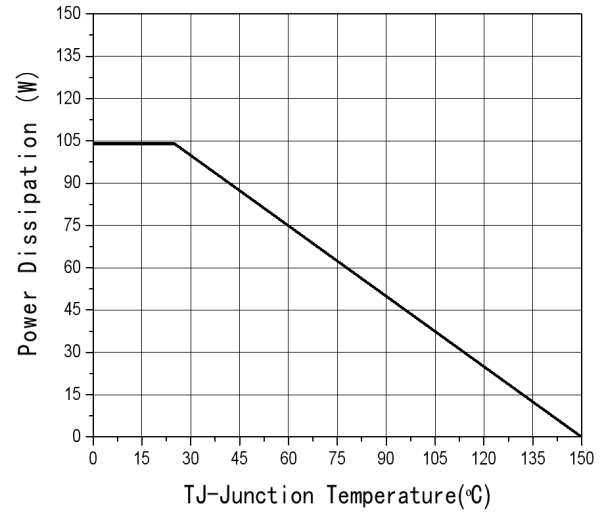


Fig6 Gate Charge



**Fig7 Rds-on-Gate Drain voltage**



**Fig8 Power De-rating**

Figure A: Gate Charge Test Circuit & Waveforms

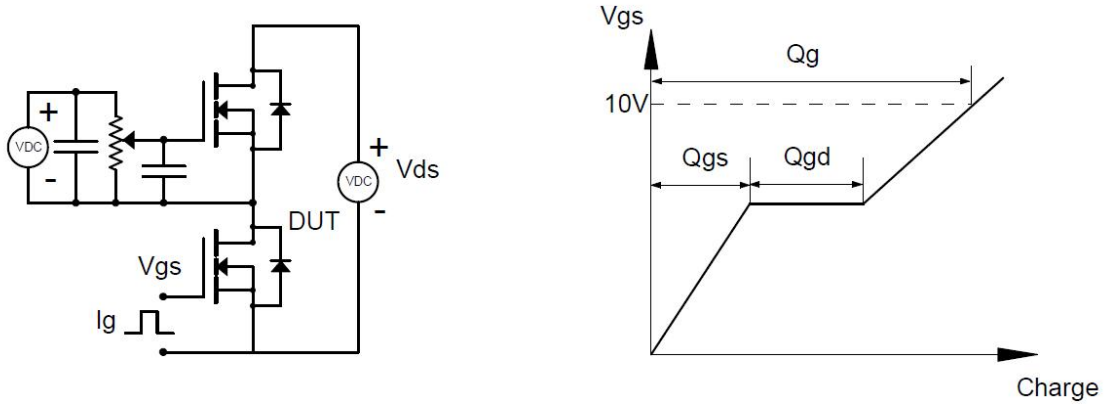


Figure B: Resistive Switching Test Circuit & Waveforms

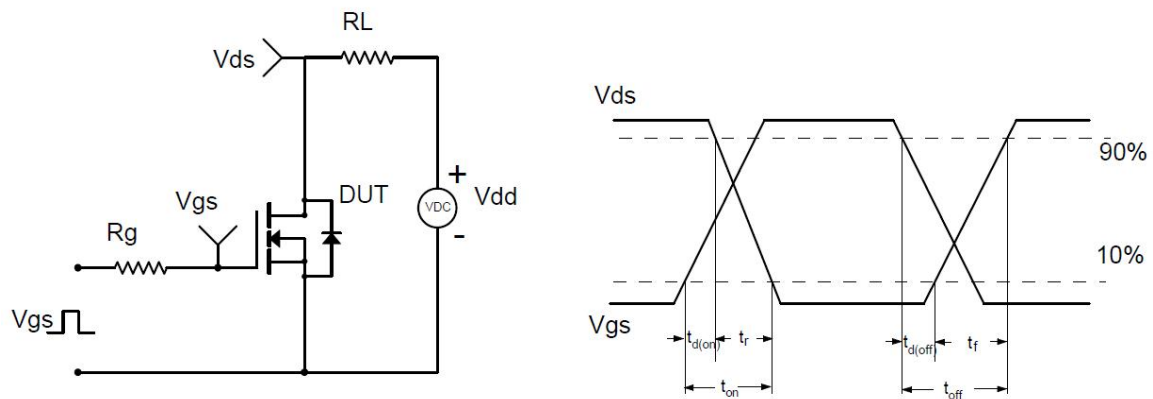


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

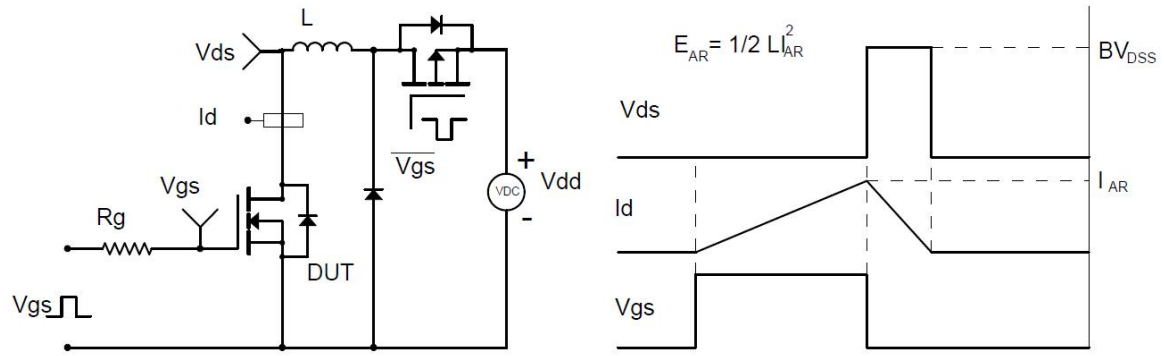
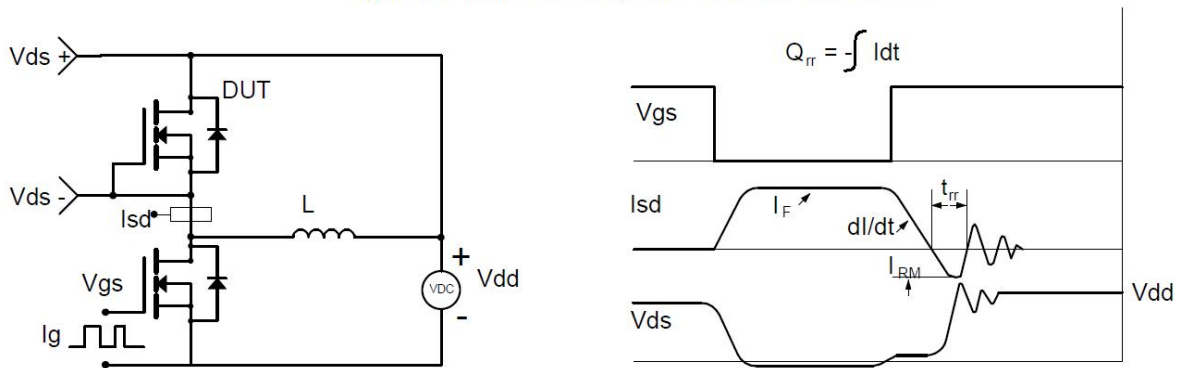
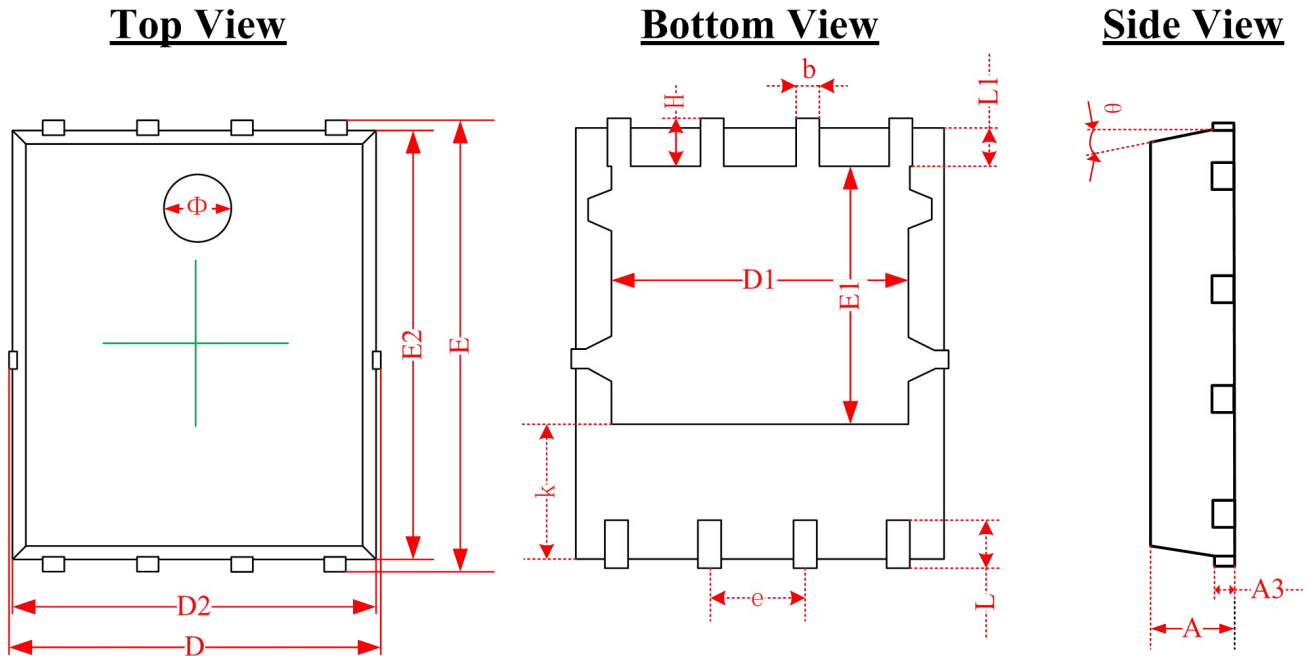


Figure D: Diode Recovery Test Circuit & Waveforms



## Package Information

- PDFN5\*6-8L-A



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.870	0.900	0.930	0.034	0.035	0.036
A3	0.203REF.			0.008REF.		
D	4.944	5.020	5.096	0.195	0.198	0.201
E	5.974	6.050	6.126	0.235	0.238	0.241
D1	3.910	4.010	4.110	0.154	0.158	0.162
E1	3.375	3.475	3.575	0.133	0.137	0.141
D2	4.870	4.900	4.930	0.192	0.193	0.194
E2	5.720	5.750	5.780	0.226	0.227	0.228
k	1.190	1.290	1.390	0.047	0.051	0.055
b	0.350	0.380	0.410	0.014	0.015	0.016
e	1.270TYP.			0.050TYP.		
L	0.559	0.635	0.711	0.022	0.025	0.028
L1	0.424	0.500	0.576	0.017	0.020	0.023
H	0.574	0.650	0.726	0.023	0.026	0.029
$\theta$	10°	11°	12°	10°	11°	12°
$\Phi$	1.150	1.200	1.250	0.045	0.047	0.049